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Part Number:

0783590111

Status:

Active

Overview:

DDR3 DIMM Sockets

Description:

1.00mm Pitch DDR3 DIMM Socket, Very Low Profile, 25° Angle, Through Hole, with Beveled Metal Pins, Black Housing and Latches, 0.76µm Gold (Au) Plating, 4.00mm Solder Tail Length, 2.59mm PCB Thickness, 1.5V Center Voltage Key,

Documents:

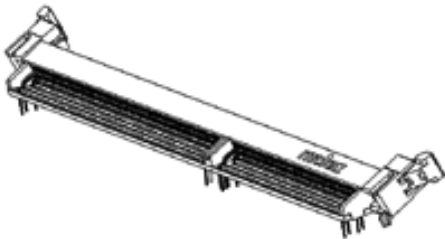
3D Model

Drawing (PDF)

Product Specification PS-78359-001-001 (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification	
CSA	LR19980
UL	E29179
Application tooling part link	
Application Tooling Part Link	62100-1960
General	
Product Family	Memory Module Sockets
Series	78359
Component Type	Socket
Electrical Model	Yes
JEDEC Outline	MO-269
Overview	DDR3 DIMM Sockets
Product Name	DDR3 DIMM
UPC	883906302191
Physical	
Circuits (Loaded)	240
Circuits (maximum)	240
Durability (mating cycles max)	25
Entry Angle	25° Angle
Flammability	94V-0
Function Key	None
Housing Color	Black
Keying to Mating Part	Yes
Latch Color	Black
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	10.866/g
PC Tail Length	4.00mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	2.59mm
Packaging Type	Tray
Pitch - Mating Interface	1.00mm
Pitch - Termination Interface	1.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Temperature Range - Operating	-55° to +85°C
Termination Interface: Style	Through Hole
Electrical	
Current - Maximum per Contact	1.0A
Voltage - Maximum	30V AC (RMS)/DC



Series image - Reference only

EU ELV	
Not Relevant	
EU RoHS	China RoHS
Compliant	
REACH SVHC	
Not Contained Per - ED/71/2019 (16 July 2019)	
Halogen-Free	
Status	
Not Low-Halogen	
For more information, please visit Contact US	
China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

78359 Series

Mates With

JEDEC Standard 1.27mm Modules

Application Tooling | [FAQ](#)

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
MiniDIMM Memory	621001960
Card Insertion Tool	

Voltage Key	Center
Solder Process Data	
Duration at Max. Process Temperature (seconds)	010
Lead-freeProcess Capability	SMC&WAVE
Max. Cycles at Max. Process Temperature	002
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Electrical Model Document	EE-78359-001
Product Specification	PS-78359-001-001
S-Parameter Model	SP-78359-001
Sales Drawing	SD-78359-001-001

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